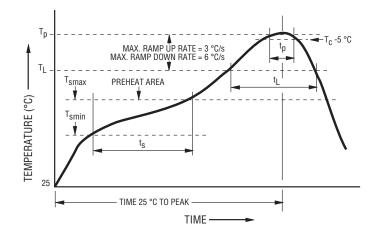
SF-1206HHxxM Series - High Current & High Inrush Multilayer Surface Mount Fuses

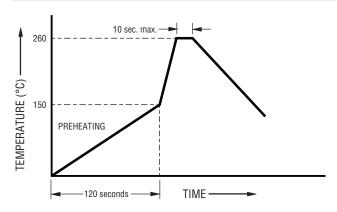
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Solder Reflow Recommendations



Profile Feature	Pb-Free Assembly
Preheat / Soak:	
Temperature Min. (T _{smin})	150 °C
Temperature Max. (T _{smax})	200 °C
Time (t _s) from (T _{smin} to T _{smax})	60~120 seconds
Ramp Up Rate (T_L to T_p)	3 °C / second max.
Liquidous Temperature (TL)	217 °C
Time (t_L) maintained above T_L	60~150 seconds
Peak Package Body Temperature (T _p)	260 °C
Time $(t_p)^*$ within 5 °C of the specified classification temperature (T_c)	30 seconds*
Ramp Down Rate $(T_p \text{ to } T_L)$	6 °C / second max.
Time 25 °C to Peak Temperature	8 minutes max.

* Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.



Recommended Temperature Profile for Wave Soldering

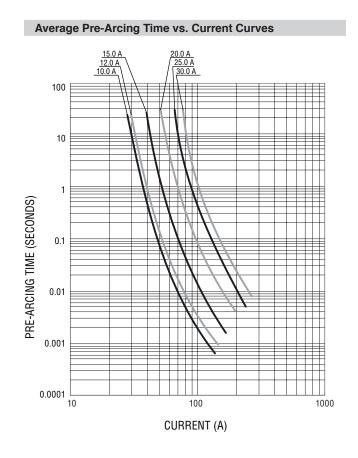
Wave soldering is suitable for 1206 size models.

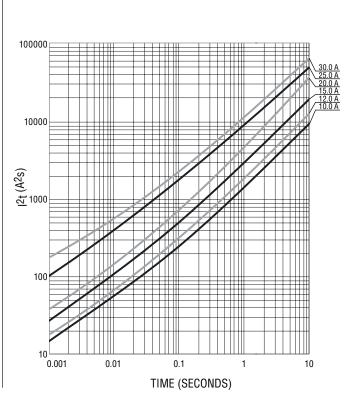
Specifications are subject to change without notice. Users should verify actual device performance in their specific applications.

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Average I²t vs. t Curves

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